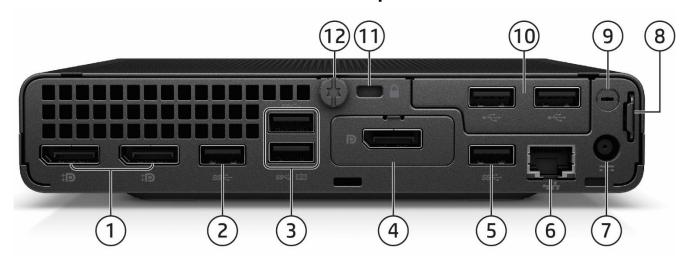
HP EliteDesk 805 G6 Desktop Mini Business PC



- Type-C[™] SuperSpeed USB 10Gbps signaling rate (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 10 Gbps signaling rate
- 3. Type-A SuperSpeed USB 10 Gbps signaling rate (charge support up to 5V/3A)
- 4. Universal Audio Jack with CTIA headset support
- 5. Dual-state power button
- 6. Hard Drive activity light



HP EliteDesk 805 G6 Desktop Mini Business PC



- 1. (2) DisplayPort™ 14
- 2. Type-A SuperSpeed USB 10Gbps signaling rate
- 3. 2 x Type-A SuperSpeed USB 5Gbps signaling rate (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 4. (1) Flex Port 1*, choice of:
 - DisplayPort™ 1.4 (shown here installed)
 - HDMI 2.0a
 - VGA
 - 2.5 GbE Ethernet NIC
- (2) Type A SuperSpeed USB 5Gbps signaling rate
- Type-C[®] SuperSpeed USB 10Gbps signaling rate port w/Alt Mode DisplayPort™
- Fiber NIC (1Gbps or 100 MBps)

- 6. RJ-45 Network Adapter
- 7. Power connector
- 8. Retractable Padlock Loop
- 9. External WLAN antenna opening
- 10. (1) Flex Port 2, choice of:
 - VR Ready NVIDIA GTX 1660 Ti discrete GPU
 - (2) Type-A Hi-Speed USB 480Mbps signaling rate port (shown here installed)
 - Serial
- 11. Standard cable lock slot (10mm)
- 12. Cover release thumbscrew

5. Type-A SuperSpeed USB 10Gbps signaling rate

Not Shown

Slots (1) internal M.2 WLAN (2230 connector)

(2) internal M.2 SSD storage (2280 connector)

Bays (1) 2.5- inch SATA drive Bay

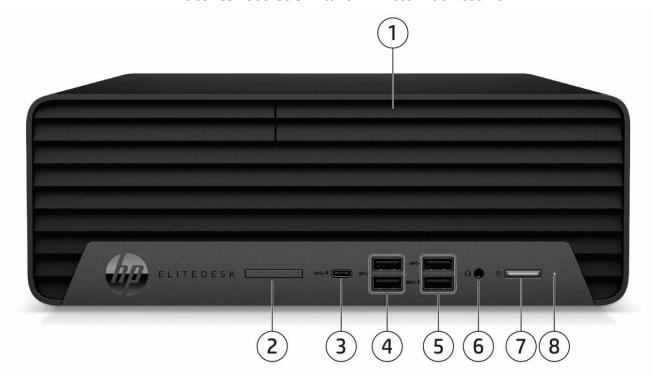
Mounting VESA 100 mounting system integrated on bottom of PC chassis

Support for:

- VESA Sleeve standalone
- Quick Release Bracket
- B300/B500 Mounting bracket
- Integrated Work Center Stand

*NOTE: Availability depends on model

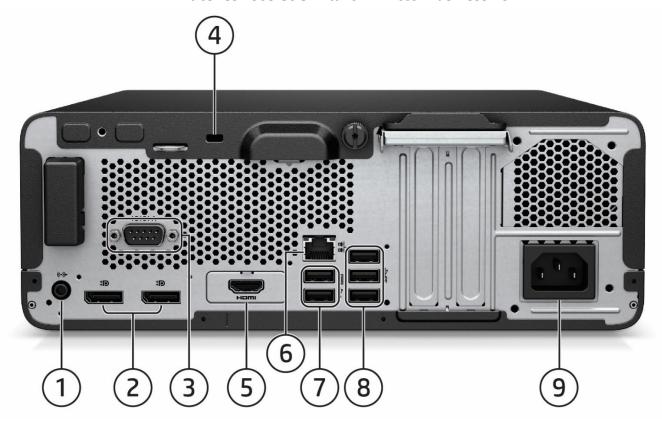
HP EliteDesk 805 G6 Small Form Factor Business PC



- 1. 9.5mm slim optical drive (optional)
- 2. SD 4 media card reader (optional)
- 3. USB-C® SuperSpeed USB 10Gbps signaling rate (charge support up to 5V/3A)
- 4. (2) Type A SuperSpeed USB 10Gbps signaling rate
- (2) Type A SuperSpeed USB 5Gbps signaling rate (fast charging)
- 6. Universal Audio Jack with CTIA headset support
- 7. Dual-state power button
- 8. Hard Drive activity light



HP EliteDesk 805 G6 Small Form Factor Business PC



- 1. Audio line-out connector
- 2. (2) DisplayPort™ 1.4
- 3. Optional serial port (shown here installed)
- 4. Standard lock slot
- 5. Optional Flex Port, choice of:
 - DisplayPort™ 1.4
 - HDMI 2.0a (shown here installed)
 - VGA
 - Serial
- (2) Type A SuperSpeed USB 5Gbps signaling rate
- Type-C[®] SuperSpeed USB 10Gbps signaling rate port w/Alt Mode DisplayPort™

- 6. RJ-45 Network Adapter
- 7. 2 x Type A Hi-Speed USB 480MBps signaling rate (one with wake from keyboard)
- 8. 3 x Type A SuperSpeed USB 5Gbps signaling rate
- 9. Power connector

Slots

- (1) PCI Express x16 graphics connectors
- (1) PCI Express x4
- (1) internal M.2 WLAN (2230 connector)
- (2) internal M.2 SSD storage (2280 connector)

Rave

- (1) 3.5" internal storage drive bay (convertible to two 2.5", requiring adapter supplied from factory only)
- (1) 9.5mm slim optical drive bay



Standard Features and Configurable Components (availability may vary by country)

AT A GLANCE

- Choice of two form factors: Small Form Factor and Desktop Mini
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability
- AMD® Ryzen™ PRO 4000 series processors with Radeon™ Vega Graphics¹
- Support for up to 7 monitors on DM² and 6 monitors on SFF via two standard DisplayPort™ 1.2, a configurable flex port for video and a discrete graphics card.⁷
- Configurable flex port provides the following choices: HDMI 2.0a, VGA, DisplayPort™ 1.4, USB Type-C™ with DisplayPort™ 1.2 for all platforms; 2nd serial or dual USB Type-A for SFF, USB Type-C™ with DisplayPort™ 1.2 with 100W Power Delivery for DM and discrete graphics with Display Port™ 1.4 for DM with 35W (see Ports section for port availability by platform).
- 2nd flex port available for DMs with the choice of Serial and dual USB Type-A.
- Intel® Wi-Fi® 6 + BT5 (802.11AX 2x2)³
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 3200 MT/s)⁶
- Compatibility with HP Mini-In-One 24 Display⁴ (DM)
- Configurable NVIDIA® GeForce®VR ready discrete graphics card with (3) Mini DisplayPort™ and (1) micro-HDMI video port for DM to support up to (7) monitors with minimum 4K resolution.⁷
- Configurable NVIDIA® Quadro® discrete graphics card with (3) Mini DisplayPort™ for SFF to support up to (6) monitors with minimum 4K resolution.^{2,7}
- Compatible with HP Reverb VR Headset (DM)
- Models can be configured with dual data drives in a RAID array
- Industry-standard AMD® DASH manageability with full featured KVM
- Enhanced security with HP Security Suite (Refer to Security Section for details)
- ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.
- CCC, CECP and SEPA Certified
- TCO certified
- PC chassis and all internal components and modules are manufactured with low halogen content⁵
- Dust filter available (SFF and DM 35W)
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1/UL62368-1) / CSA (CSA C22.2 No.62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)
- 1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
- 2. Only available on Desktop Minis with 35W processor.
- 3. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi® 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi® 6 (802.11ax) may affect the ability of the PC to communicate with other 802.11ax devices.
- 4. HP Mini-in-One 24 Display sold separately. PC must be configured with optional USB Type-C™ with DisplayPort™ 1.2 with 100W Power Delivery
- 5. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be low halogen.
- 6. Transfer rates determined by processor and memory configuration
- 7. Configurable VGA port does not support 4K resolution.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Components (availability may vary by country)

PRODUCT NAME

HP EliteDesk 805 G6 Desktop Mini Business PC HP EliteDesk 805 G6 Small Form Factor Business PC

OPERATING SYSTEM

Preinstalled Windows® 10 Pro 64¹ - HP recommends Windows 10 Pro¹

Windows® 10 Pro 64 (National Academic License)2

Windows® 10 Home 641

Windows® 10 Home Single Language 64¹ Windows® 10 Enterprise 64 (Web support)¹

FreeDos

1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

SUPPORTED VERSIONS

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

CHIPSET

	<u>DM</u>	<u>SFF</u>
AMD® PRO 565	X	X



Standard Features and Configurable Components (availability may vary by country)

PROCESSORS¹

AMD® Ryzen™ 4000 series Desktop Processors with PRO technologies and integrated AMD® Radeon™ Graphics	<u>DM</u>	<u>SFF</u>
AMD Ryzen™ 7 PRO 4750G Processor (8C/16T, 12 MB cache, 4.4GH Boost) 65W	Х	Х
AMD Ryzen™ 7 PRO 4750GE Processor (8C/16T, 12MB cache, 4.3GHz Boost) 35W	Х	
AMD Ryzen™ 5 PRO 4650G Processor (6C/12T, 11MB cache, 4.2GHz Boost) 65W	X	Х
AMD Ryzen™ 5 PRO 4650GE Processor (6C/12T, 11MB cache, 4.2GHz Boost) 35W	X	
AMD Ryzen™ 3 PRO 4350G Processor (4C/8T, 6MB cache, 4.0GHz Boost) 65W	X	Х
AMD Ryzen™ 3 PRO 4350GE Processor (4C/8T, 6MB cache, 4.0GHz Boost) 35W	Х	

^{1.} Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.



Standard Features and Configurable Components (availability may vary by country)

GRAPHICS

Х	Х
<u>DM</u>	<u>SFF</u>
	Х
	Х
	Х
	X
	Х
Х	
	<u>DM</u>

^{1.}Not available in all regions.

^{2.} Only available on the Desktop Mini with 35W Processor

dapters and Cables	<u>DM</u>	<u>SFF</u>
HP DisplayPort™ Cable	Х	X
HP DisplayPort™ to DVI-D Adapter	Х	Х
HP DisplayPort™ to HDMI 4K Adapter	Х	X
HP DisplayPort™ to VGA Adapter	Х	Х
HP USB to Serial Port Adapter	Х	Х
HP USB-C® to HDMI 4K Adapter	Х	Х
HP USB-C® to DisplayPort Adapter	Х	Х
HP DVI Cable	Х	Х
Micro HDMI to HDMI Adapter	Х	
Mini DisplayPort to DisplayPort Adapter	Х	

STORAGE

.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>
HDD 500GB 7200RPM 3.5in		X
HDD 1TB 7200RPM SATA-3 3.5in		X
HDD 2TB 7200RPM SATA-3 3.5in		X
	·	

2.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>
HDD 2 TB 5400RPM 2.5in	X	X
HDD 500GB 7200RPM 2.5in	X	X
HDD 1TB 7200RPM 2.5in	X	X
HDD 500GB 7200RPM 2.5in Self Encrypted Drive OPAL2*	X	X
HDD 500GB 7200RPM 2.5in Federal Information Processing Standard*	X	X

NOTE*: Storage Drivelock does not work with Self Encrypting storage.



Standard Features and Configurable Components (availability may vary by country)

1.2 PCIe NMVe Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>
256GB M.2 2280 PCIe NVMe SSD	Х	X
512GB M.2 2280 PCIe NVMe SSD	Х	Х
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	Х	Х
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD *	Х	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD *	Х	Х

NOTE*: Storage Drivelock does not work with Self Encrypting storage.

Optical Disc Drive	s	<u>DM</u>	<u>SFF</u>
HP 9.5mm Sl	im DVD-ROM Drive		Х
HP 9.5mm Sl	im DVD Writer Drive		Х
HP 9.5mm Sl	im Blu-Ray Writer Drive		Х

Media Card Reader	<u>DM</u>	<u>SFF</u>
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		X

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

MEMORY^{1,2}

Max Memory Configuration	<u>DM</u>	<u>SFF</u>
DDR4-3200 (Transfer rates up to 3200 MT/s), 64 GB, 2 SODIMM	X	
DDR4-3200 (Transfer rates up to 3200 MT/s), 128 GB, 4 DIMM		X

^{1.} All memory slots are customer accessible/upgradeable.

^{2.} Actual transfer rate will vary and is determined by the system's configured processor. See processor specifications for supported memory data rate.

emory Configuration	<u>DM</u>	<u>SFF</u>
4 GB (1 x 4 GB)	X	Х
8 GB (2 x 4 GB)	X	Х
8 GB (1 x 8 GB)	X	Х
16 GB (2 x 8 GB)	X	Х
16 GB (1 x 16 GB)	X	X
32 GB (2 x 16 GB)	X	Х
32 GB (4 x 8 GB)		X
32 GB (1 x 32 GB)	X	Х
64 GB (4 x 16 GB)		X
64 GB (2 x 32 GB)	X	X



Standard Features and Configurable Components (availability may vary by country)

128 GB (4 x 32 GB)	v
120 db (4 x 32 db)	Λ

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)	<u>DM</u>	<u>SFF</u>
Realtek® RTL8111FP (standard) ¹	X	X

1. Supports full-featured AMD DASH and hardware enforced KVM

Vireless ¹	<u>DM</u>	<u>SFF</u>
Intel® Wi-Fi 6 AX200 (2x2) and Bluetooth® M.2 Combo Card²	Х	X
Realtek RTL8822CE Wi-Fi 5 (2x2) and Bluetooth® 5 Combo	X	Х
Realtek RTL8822CE Wi-Fi 5 (2x2) and Bluetooth® 5 Combo with external antenna	X	

^{1.} Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

KEYBOARDS AND POINTING DEVICES

boards	<u>DM</u>	<u>SFF</u>
HP Wired Desktop 320K Keyboard	Х	Х
HP USB Premium Keyboard	Х	Х
HP USB and PS/2 Washable Keyboard	Х	Х
HP USB Smart Card (CCID) Keyboard	Х	Х
HP USB Keyboard	Х	Х
HP PS/2 Business Slim Keyboard		Х
HP Wireless Business Slim Keyboard and Mouse	Х	Х
HP USB Business Slim Antimicrobial Keyboard ¹	Х	Х
HP Wireless Premium Keyboard and Mouse	Х	Х
HP USB Keyboard and Mouse Healthcare Edition	X	X
HP Wireless Premium Keyboard	х	Х

1. China only

W

Mouse	<u>DM</u>	<u>SFF</u>
HP Wired Desktop 320M Mouse	Х	Х
HP PS/2 Mouse		X
HP USB Optical Wired Mouse	Х	X
HP USB Premium Mouse	Х	X
HP 1000dpi Laser Mouse USB	Х	X
HP USB and PS/2 Washable Mouse	Х	X
Antimicrobial USB Mouse ¹	Х	Х
HP Hardened Optical USB Mouse ¹	Х	X



^{2.} Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi® 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.

Standard Features and Configurable Components (availability may vary by country)

HP USB Fingerprint Reader Mouse	X	X

1. China only

SECURITY

	<u>DM</u>	<u>SFF</u>
TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	X	X
Intrusion Sensor (Optional)		Х
Intrusion Sensor (integrated in the system board, can be enabled/disabled through BIOS)	X	
Support for chassis cable lock devices	X (10 mm barrel or smaller)	X
Support for chassis padlocks devices	Х	Х
SATA port disablement (via BIOS)	X	X
Serial, USB enable/disable (via BIOS)	Х	Х
Removable media write/boot control	Х	Х
Power-on password (via BIOS)	Х	Х
Setup password (via BIOS)	X	Х

PORTS

1/0	Ports – Internal Ports	<u>DM</u>	<u>SFF</u>
	Internal SATA storage connector(s)	N/A	(3)
	Internal SATA storage connector (Data and Power)	(1)	N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option). (Not applicable to all regions.)

I/O Ports – Standard	<u>DM</u>	<u>SFF</u>
Hi-Speed USB 480Mbps signaling rate port		2 rear
Type-A SuperSpeed USB 5 Gbps signaling rate port	(2) (rear)	(2) (front);3 (rear)
Type-A SuperSpeed USB 10 Gbps signaling rate port	(2) (front);2 (rear)	(2) (front)
Type-C [®] SuperSpeed USB 10 Gbps signaling rate port (15W)	(1)(front)	(1) (front)
Video	(2) DisplayPort™ 1.4 (rear)	(2) DisplayPort™ 1. 4 (rear)
Audio	(1) Universal Audio Jack with CTIA headset support (front);	(1) Universal Audio Jack with CTIA headset support (front); (1) Audio-out (rear)
Network Interface	RJ45	RJ45

I/O Ports – Optional <u>DM</u> <u>SFF</u>



Standard Features and Configurable Components (availability may vary by country)

Serial (RS-232)	N/A	1 (rear)
Serial (RS-232) and PS/2 combination	N/A	1 (rear) ¹

1. Occupies PCIe slot



Standard Features and Configurable Components (availability may vary by country)

(1) Flexible Port 1 – Optional (rear), choice of one of the following	<u>DM</u>	<u>SFF</u>
Type-A SuperSpeed USB 5 Gbps signaling rate port	2	2
Type-C [®] SuperSpeed USB 10Gbps signaling rate port	(1) w/DisplayPort™1.2 Alt Mode and power intake via USB Type-C® Power Delivery up to 100W	(1) w/ DisplayPort™ 1.2 Alt Mode
Video	(1) DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA	(1) DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA
Serial (RS-232)	N/A	(1)
Fiber NIC	(1) 100Mbps NIC (1) 1 Gbps NIC	N/A
RJ-45 Ethernet NIC	(1) 2.5Gbps	N/A
(1) Flexible Port 2 – Optional (rear), choice of one of the following:	<u>DM</u>	<u>SFF</u>

ne of the following:		<u>=</u>
Type-A Hi-Speed USB 480Mbps signaling rate port	(2)	N/A
Serial (RS-232)	(1)	N/A
Discrete Graphics 1	(1)	N/A

^{1.} Only available on the Desktop Mini with 35W Processor

Slots	<u>DM</u>	<u>SFF</u>
M.2 PCIe	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280 (for storage)	(1) M.2 PCle x1 2230 (for WLAN) (2) M.2 PCle x4 2280 (for storage)
PCI Express v3.0 x4	N/A	1
PCI Express v3.0 x16	N/A	1
Bays	<u>DM</u>	<u>SFF</u>
9.5mm Slim ODD	N/A	1
Secure Digital (SD) Reader	N/A	1
2.5" internal storage drive	1 (optional)	21

^{1.} SFF can be configured with either (1) 3.5" or (2) 2.5" internal storage drive (2.5" requiring adapter supplied from factory only) SATA 2.5" internal storage drive cannot be selected if 2nd M.2 SSD or discrete graphic card, or 95W processor is selected

USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



HP EliteDesk 805 G6 Business Desktops PCs

QuickSpecs

Standard Features and Configurable Components (availability may vary by country)



Standard Features and Configurable Components (availability may vary by country)

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen6¹⁷
HP DriveLock & Automatic DriveLock
BIOS Update via Network
Power On Authentication
HP Secure Erase¹⁸
Absolute Persistence Module¹⁹
Pre-boot Authentication
HP Wake on WLAN

Software

mvHP

HP Support Assistant²¹
HP Noise Cancellation Software
Hp Privacy Settings
HP Setup Integrated OOBE
HP PC Hardware Diagnostics Windows

Manageability Features

HP Driver Packs (download)²²
HP System Software Manager (SSM) (download)
HP BIOS Config Utility (BCU) (download)
HP Client Catalog (download)
HP Manageability Integration Kit Gen4 (download)²³
Ivanti Management Suite (download)²⁴
HP Client Management Script Library (download)
HP Image Assistant Gen5 (download)

Client Security Software

HP Client Security Manager Gen65²⁵ HP Power On Authentication Windows Defender²⁷

Security Management

Trusted Platform Module TPM 2.0 Embedded Security Chip shipped with Windows 10. Common Criteria EAL4+ Certified. SATA 0.1 port disablement (via BIOS)

Serial, USB enable/disable (via BIOS)

Power-on password (via BIOS)

Setup password (via BIOS)

Support for chassis padlocks and cable lock devices

HP Sure Start Gen6

HP Sure Click³⁴

HP Sure Run Gen335

HP Sure Recover Gen3³⁶

HP Sure Sense³⁷

17. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:



Standard Features and Configurable Components (availability may vary by country)

http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

- 21. HP Support Assistant requires Windows and Internet access.
- 22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 23. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 24. Ivanti Management Suite subscription required.
- 25 HP Client Security Manager Gen6 requires Windows and is available on the select HP Pro and Elite PCs.
- 27. Windows Defender Opt in and internet connection required for updates.
- 30. HP Sure Start Gen6 is available on select HP PCs with Intel processors
- 34. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A SureClick for complete details.
- 35. HP Sure Run Gen3 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.
- 36. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
- 37. HP Sure Sense requires Windows 10 Pro or Enterprise.
- 38. HP Sure Start Gen6 is available on select HP PCs.



Standard Features and Configurable Components (availability may vary by country)

ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.

Low halogen (chassis, all internal components and modules)² TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit
 is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the
 enclosure, and the same operating guidelines listed above will still apply.

Temperature Range Operating: 50° to 95° F (10° to 35° C)¹

Non-operating: -22° to 140° F (-30° to 60° C)

Relative Humidity Operating: 10% to 90% (non-condensing at ambient)

Non-operating: 5% to 95% (non-condensing at ambient)

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

HP EliteDesk 805 Desktop Mini G6 Business PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. • TCO Certified 8.0		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	9.9 W	10 W	9.6 W



Standard Features and Configurable Components (availability may vary by country)

	1		I		
Normal Operation (Long idle)		9.1 W	9.2	W	9 W
Sleep		0.8 W 0.8 W		0.8 W	
Off		0.7 W	0.7	W	0.7 W
	family. HP com Environmental offer ENERGY S featuring a har	puters marked with th Protection Agency (EF STAR® compliant config d disk drive, a high eff	e ENERGY STAR® Log PA) ENERGY STAR® spe gurations, then energ iciency power supply,	o are compliant with ecifications for comp y efficiency data liste and a Microsoft Wino	uters. If a model family does not ed is for a typically configured PC dows® operating system.
Heat Dissipation*	115	VAC, 60Hz	230VAC	, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	33.0	63 BTU/hr	33.93 B	TU/hr	32.88 BTU/hr
Normal Operation (Long idle)		17 BTU/hr	31.5 B		30.54 BTU/hr
Sleep		7 BTU/hr	2.7 BT		2.6 BTU/hr
Off	2.3	1 BTU/hr	2.4 BT	U/hr	2.23 BTU/hr
	NOTE: Heat dishour.	ssipation is calculated t	pased on the measure	d watts, assuming th	ne service level is attained for one
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)			ound Pressure L _{pAm} , decibels)		
Typically Configured – Idle	3.1		19		
Fixed Disk – Random writes	2.9		20		
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.				
Batteries	Batteries use Mercury grea Cadmium gre Battery size: Battery type:	in this product com d in the product do r ter the1ppm by weig ater than 20ppm by Not Applilcable Not Applilcable	oot contain: yht weight		
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <gold> level, see www.epeat.net</gold> Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. This product contains 35.2% post-consumer recycled plastic (by wt.) This product is 92.8% recycle-able when properly disposed of at end of life. 				
Packaging Materials	External:	PAPER/Corrugated			450 g
	Internal:	PAPER/Molded Pu			•
		FAFER/MULUEU PU	ıp		74 g



Standard Features and Configurable Components (availability may vary by country)

	PLASTIC/Polyethylene low dens	ty - LDPE	5 g	
Material Usage	This product does not contain any of the follow		n excess of regulatory limits (refer to	
	the HP General Specification for the Environme			
	http://www.hp.com/hpinfo/globalcitizenship/e	nvironment/pdf	/gse.pdf):	
	• Asbestos			
	Certain Azo Colorants		and the state of the state of	
	Certain Brominated Flame Retardants – may r	ot be used as fla	ame retardants in plastics	
	• Cadmium			
	Chlorinated Hydrocarbons Chlorinated Paraffins			
	Formaldehyde			
	Halogenated Diphenyl Methanes Lead carbonates and sulfates			
	Lead and Lead compounds			
	Mercuric Oxide Batteries			
	Nickel – finishes must not be used on the external surface designed to be frequently handled or			
	carried by the user.			
	Ozone Depleting Substances			
	Polybrominated Biphenyls (PBBs)			
	 Polybrominated Biphenyl Ethers (PBBEs) 			
	 Polybrominated Biphenyl Oxides (PBBOs) 			
	Polychlorinated Biphenyl (PCB)			
	Polychlorinated Terphenyls (PCT)			
	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been			
	voluntarily removed from most applications.			
	• Radioactive Substances			
De also aima Han an	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributy			
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:			
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging			
	materials.			
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.			
	Design packaging materials for ease of disassembly.			
	Maximize the use of post-consumer recycled content materials in packaging materials.			
	Use readily recyclable packaging materials such as paper and corrugated materials.			
	Reduce size and weight of packages to improve transportation fuel efficiency.			
	Plastic packaging materials are marked accor	•	<u> </u>	
End-of-life Management	HP Inc. offers end-of-life HP product return and			
and Recycling	recycle your product, please go to: http://www			
-	sales office. Products returned to HP will be rec	ycled, recovered	l or disposed of in a responsible	
	manner.			
	The EU WEEE directive (2002/95/EC) requires m			
	each product type for use by treatment facilities. This information (product disassembly			
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM			
			it racilities as well as HP UEM	
UD Inc. Corporate	customers who integrate and re-sell HP equipm		ant.	
HP Inc. Corporate Environmental	For more information about HP's commitment	o the environme	ent.	
Information	Global Citizenship Poport			
ııııvı ıııatıvıı	Global Citizenship Report			
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications			
	http://www8.hp.com/us/en/hp-information/er	vironment/ecol:	ahels html	
	http://wwwo.np.com/us/en/np-miormation/er	vii Olillielit/ Et0t	abets.iitiiit	



Standard Features and Configurable Components (availability may vary by country)

ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_ Certificate.pdf and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 805 Small Form Factor G6 Business PC

Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be				
& declarations	labeled with one or more of these marks:				
	IT ECO declaration				
	• US ENERGY STAR®				
	• EPEAT® Gold registered in the Ur	nited States. See http://www.epe	at.net for registration status in		
	your country.		-		
	TCO Certified 8.0				
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the				
	Desktop model is based on a "Typ	ically Configured Desktop".			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short idle)	14.5 W	14.6 W	14.5 W		
Normal Operation (Long idle)	13.5 W	13.6 W	13.1 W		
Sleep	0.8 W	0.8 W	0.8 W		
Off	0.7 W	0.7 W	0.7 W		
Heat Dissipation*	115VAC, 60Hz	115VAC, 60Hz 230VAC, 50Hz			
Normal Operation (Short idle)	49.6 BTU/hr	49.9 BTU/hr	100VAC, 50Hz 49.6 BTU/hr		
Normal Operation (Long idle)	46.2 BTU/hr	46.5 BTU/hr	44.8 BTU/hr		
Sleep	2.7 BTU/hr	2.7 BTU/hr	2.7 BTU/hr		
Off	2.4 BTU/hr	2.4 BTU/hr	2.4 BTU/hr		
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.				
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)		
Typically Configured – Idle	3.3		24		
Fixed Disk – Random writes Longevity and Upgrading	3.3 This product can be upgraded, pos		25		



Standard Features and Configurable Components (availability may vary by country)

	Spare parts a production.	re available throughout the warranty period and o	r for up to "5" years after the end of	
Batteries		s) in this product comply with EU Directive 2006/66	5/EC	
	Pattorios uso	d in the product do not contain:		
		•		
		ter the1ppm by weight eater than 20ppm by weight		
	Caumum gre	rater than 20ppin by weight		
	Battery size: Battery type:	CR2032 (coin cell) Lithium		
Additional Information		is in compliance with the Restrictions of Hazardous	Substances (RoHS) directive -	
	2011/65/EC.			
		duct is designed to comply with the Waste Electrica	al and Electronic Equipment (WEEE)	
	Directive – 20	t is in compliance with California Proposition 65 (Si	tate of California: Safe Drinking Water	
	-	forcement Act of 1986).	tate of Cathornia, Safe Drinking Water	
		t is in compliance with the IEEE 1680.1 (EPEAT) sta	ndard at the <gold> level, see</gold>	
	www.epeat.r		·	
	• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.			
	This product contains 42.2% post-consumer recycled plastic (by wt.)			
	 This produce 	t is 94.0% recycle-able when properly disposed of	at end of life.	
Packaging Materials	External:	PAPER/Paper	1019 g	
		PAPER/Molded Pulp	414 g	
	Internal:	PLASTIC/Polyethylene low density - LDPE	29 g	
Material Usage		does not contain any of the following substances in	n excess of regulatory limits (refer to	
	the HP General Specification for the Environment at			
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):			
	• Asbestos			
	Certain Azo Colorants Costain Prominated Flame Potardants			
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium			
	• Cadmium			
	Chlorinated Hydrocarbons Chlorinated Paraffins			
	• Formaldehyde			
	Halogenated Diphenyl Methanes			
	Lead carbonates and sulfates			
	• Lead and Lead compounds			
	Mercuric Oxide Batteries			
	Nickel – finishes must not be used on the external surface designed to be frequently handled or			
	carried by the user.			
	Ozone Depleting Substances			
	Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Sthore (PBBs)			
	Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Ovides (PBBCs)			
	Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCR)			
	Polychlorinated Biphenyl (PCB) Polychlorinated Torphonyls (PCT)			
	Polychlorinated Terphenyls (PCT) Polych			
	Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.			
	voluntarily removed from most applications. • Radioactive Substances			
	Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)			
	Thoutyt IIII	TIDIT, IMPLICITY THE LITE IT, INDUCYCUM ONICE (IDIC	<i>-</i> 1	



Standard Features and Configurable Components (availability may vary by country)

Packaging Usage

HP follows these quidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Standard Features and Configurable Components (availability may vary by country)

SERVICE AND SUPPORT

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR® certified. EPEAT® 2019 registered where applicable. EPEAT® registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.



Technical Specifications – Processors

PROCESSORS

AMD® Ryzen™ 4000 Series Processors

All HP EliteDesk 805 G6 Business PC are designed to ensure stability.

Architecture: "Zen 2" Process Node: 7nm

AMD® PRO Technologies

AMD® Memory Guard – Helps defend against cold boot attacks with real time encryption of memory AMD® PRO manageability – DASH including KVM Redirection Profile with hardware enforcement



Technical Specifications – Processors

GRAPHICS

AMD Radeon™ Vega 7 Graphics

Multi Display Support Maximum of 3 displays supported by the integrated graphics

DisplayPort Two DisplayPort outputs are standard. One DisplayPort output is optional.

AMD® PRO APUs and AMD® Ryzen™ APUs support

DP1.4 features including DP++, Audio, MST, HBR2, HDCP2.3 and a maximum resolution of

5128x3880@30Hz or 3840x2160@60Hz.

VGA Port (Optional) Maximum Resolution of 2048x1536 at 60Hz

HDMI (Optional) AMD® PRO APUs support HDMI 2.0 features and AMD® Ryzen™ APUs support HDMI 2.0a features.

All support HDCP2.3, audio and a maximum resolution of 4096x2160@60Hz

USB-C (Optional) Supports DisplayPort Alt Mode

Memory 512MB when less than 8GB of system memory is installed

1GB when 8GB or more of system memory is installed

Maximum Color Depthup to 10 bitsGraphics/Video API SupportAMD® PRO APUs:

DirectX 12 OpenCL 1.2 OpenGL 4.1

Dedicated decoding of the H.264 format at up to 4K and 60Hz.

Encoding H.264 video supported at 1080p120, 1440p60, and 2160p60

AMD® Ryzen™ APUs:

DirectX 12 Vulkan 1.0 OpenCL 2.0 OpenGL 4.5

Hardware-based decode of HEVC/H.265 main10 profile videos at resolutions up to 3840x2160 at

60Hz with 10-bit color for HDR content.

Dedicated decoding of the H.264 format at up to 4K and 60Hz.

Decoding the VP9 format at resolutions up to 3840x2160 using a hybrid approach where the

video and shader engines collaborate to offload work from the CPU. Encode HEVC/H.265 at 1080p240, 1440p120, and 2160p60.

Encoding H.264 video is also supported at 1080p120, 1440p60, and 2160p60



Technical Specifications – Processors

AMD® Radeon™ RX 550X 4GB PCIe x16

Engine Clock1183MHzMemory Clock6 GbpsMemory Size(width)4 GB(128-bit)

Memory Type GDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors(bracket)HDMI, DP

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP (low profile) PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 DP+VGA Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB (64-bit)Memory Type256M x 32 GDDR5Max. Resolution(VGA)2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors(bracket)DP+VGA

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB 2DP Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB(64-bit)Memory Type256M x 32 GDDR5Max. Resolution(DP)4096x2160@60Hz

Multi Display Support2 displaysHDCP ComplianceYesRear I/O connectors(bracket)DPx2

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

Engine Clock 780 MHz



Technical Specifications – Processors

GFX Nvd GeF GTX1660Ti 6GB Graphics Card

Engine Clock1140 MHzMemory Clock6001 MHzMemory Size(width)6GB (192-bit)

 Memory Type
 2CH x 256M x 16 GDDR6

 Max. Resolution(DP)
 5120 x 3200 @60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) mDPx3 + Micro HDMIx1

Cooling(active/passive) Active

Total power consumption(W) <60W

PCB form-factor with bracket Customized

Nvidia® GeFORCE® GTX1660 Ti

Architecture Discrete GPU

Nvidia® GPU drives the integrated panel and all of the graphics output ports

DisplayPort Maximun pixel clock :1.3 GHz pixels per second

Maximun bandwidth: 25.92 Gbps per connector (FEC Disable)

HDMI Supports HDMI 2.0 features

Supports HDCP 2.2, HDR

Memory 6GByte, 192bit wide GDDR6

Maximum Color Depth up to 12 bits/color

Graphics/Video API Support DirectX 12

OpenGL 4.6

Display Port Support DP1.4(DSC1.2a)

Maximum pixel clock: 1.3 GHz pixels per second

Maximum bandwidth: 25.92 Gbps per connector (FEC Disable)

Max. Resolution (HDMI) 4096 x 2160@60Hz

Max. Resolution (DP) 5120 x 3200@60Hz Example of maximum resolutions with CVT-RB timings

Port Availability (3) Mini DP 1.4 ports and (1) Micro HDMI 2.0 port

NVIDIA® Quadro P400 2GB Graphics Card

Engine Clock1252 MHzMemory Clock2000 MHzMemory Size(width)2GB (64-bit)Memory Type256M x 32 GDDR5

Max. Resolution(DP)3 displaysMulti Display SupportYesHDCP CompliancemDPx3

Rear I/O connectors(bracket) Active fan-sink (Active cooling with dynamic speed)

Cooling(active/passive) <30W

Total power consumption(W) LP PCB with LP bracket

PCB form-factor with bracket 1252 MHz



Technical Specifications – Storage

STORAGE

3.5 inch SATA HARD DISC DRIVES (HDD)

500 GB 7200RPM 3.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6.0 Gb/s

Buffer Size 32 MB

 Logical Blocks
 976,773,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity1 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1 in/2.54 cm

Width Media diameter: 3.5 in/8.89 cm

Physical size: 4 in/10.2 cm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity2 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size64 MB

 Logical Blocks
 1,953,525,168

 Seek Time
 11 ms (Average)

 Height
 1.028 in/26.11 mm



Technical Specifications – Storage

Width (nominal) 4.0 in/101.6 mm

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2.5 inch SATA HARD DISC DRIVES (HDD)

2 TB 5400RPM 2.5in SATA HDD

Capacity 2 TB

Rotational Speed 5,400 rpm **Interface** SATA 6 Gb/s **Buffer Size** 128 MB

Logical Blocks 3,907,050,336 **Seek Time** 12 ms (Average)

Height0.374 in/9.5 mm (nominal)Width (nominal)2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in SATA HDD

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size16 MBLogical Blocks976,773,168Seek Time12 ms (Average)

Height0.267 in/7.2 mm (Maximum)Width2.75 in/70 mm (nominal)Operating Temperature41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 2.5in SATA HDD

Capacity 1 TB

Rotational Speed 7,200 rpm
Interface SATA 6 Gb/s
Buffer Size 32 MB

Logical Blocks 1,953,525,168



Technical Specifications – Storage

Seek Time 12 ms (Average)

 Height
 0.374 in/9.5 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity 500 GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

InterfaceSATA 6 Gb/sBuffer Size128 MBLogical Blocks976,773,168Seek Time12 ms (Average)

 Height
 0.267 in/7.2 mm (Maximum)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 2.5" FIPS 140-2 SED Solid State Drive

Drive Weight 500 GB

Capacity Self-Encrypting (SED) Solid State Drive with SATA interface

 Height
 SATA 6 Gb/s

 Length
 128 MB

 Width
 976,773,168

 Interface
 12 ms (Average)

Maximum Sequential Read0.267 in/7.2 mm (max.)Maximum Sequential Write2.75 in/70 mm (nominal)Logical Blocks41° to 131° F (5° to 55° C)

Operating Temperature 500 GB

Features Self-Encrypting (SED) Solid State Drive with SATA interface

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Technical Specifications – Storage

M.2 PCIe NMVe SOLID STATE DRIVES (SSD)

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 256 GB Height 2.38mm 80mm Length Width 22mm Interface PCIE Gen3 Up to 1600MB/s **Maximum Sequential Read Maximum Sequential Write** Up to 780MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight < 10q Capacity 512 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3 **Maximum Sequential Read** Up to 1600MB/s **Maximum Sequential Write** Up to 860MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10q Capacity 128 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2800MB/s **Maximum Sequential Write** Up to 600MB/s **Logical Blocks** 250,069,680



Technical Specifications – Storage

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a 256GB Capacity 2.38mm Height Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2700MB/s **Maximum Sequential Write** Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

< 10q **Drive Weight** Capacity 512 GB 2.38mm Height Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight< 10g</td>Capacity1 TBHeight2.38mmLength80mmWidth22mm



Technical Specifications – Storage

InterfacePCIE Gen3x4Maximum Sequential ReadUp to 3480MB/sMaximum Sequential WriteUp to 3037MB/sLogical Blocks2,000,409,264

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight < 10a Capacity 2 TB Height 2.38mm Length 80mm Width 22_{mm} Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 3000MB/s **Maximum Sequential Write** Up to 2900MB/s **Logical Blocks** 3,907,029,168

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10a Capacity 256 GB Height 2.38mm Length 80mm Width 22mm Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2700MB/s Maximum Sequential Write Up to 1000MB/s **Logical Blocks** 500,118,192

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight < 10g



Technical Specifications – Storage

Capacity 512 GB Height 2.38mm Length 80mm Width 22_{mm} Interface PCIE Gen3x4 **Maximum Sequential Read** Up to 2900MB/s **Maximum Sequential Write** Up to 1100MB/s **Logical Blocks** 1,000,215,216

Operating Temperature 0° to 70°C (32° to 158°F) [ambient temp]

Features APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

OPTICAL DISC DRIVES

HP 9.5mm Slim DVD-ROM Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) Up to 0.31 lb (140q) without bezel

Read Speeds DVD+R/-R/+RW/

-RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X

Access time

(typical reads, including

settling)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical)

Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Environmental conditions

Temperature 41° to 122° F (5° to 50° C)

(operating - non- Relative Humidity 10% to 80%

condensing) Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height 9.5 mm height

Orientation Either horizontal or vertical

Interface type SATA/ATAPI

Disc recording capacity Up to 8.5 GB DL or 4.7 GB standard

Dimensions (W x H x D) 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

Weight (max) 0.31 lb (140 g)

Write Speeds DVD-R DL - Up to 6X

DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X



Technical Specifications – Storage

DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X

Read Speeds DVD-RW, DVD+RW - Up to 8X

> DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X

DVD-ROM DL. DVD-ROM - Up to 8X

CD-ROM, CD-R - Up to 24X

CD-RW - Up to 24X

Access time

(typical reads, including

settling) **Power**

Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)

Stop Time 6 seconds (typical)

Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)

Environmental conditions

(operating - noncondensing)

Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80%

Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height 9.5 mm height

Either horizontal or vertical Orientation

Interface type SATA/ATAPI

Disc recording capacity Dimensions (W x H x D)

Weight (max) **Write Speeds**

Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL 5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel

0.29 lb (132 g) BD-R SL/DL Up to 6X BD-R TL/QL Up to 4X BD-RE Up to 2X DVD-R Up to 8X DVD-R DL - Up to 6X DVD-RW Up to 6X

DVD+R Up to 8X DVD+R DL - Up to 6X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X

Read Speeds BD-ROM Up to 6X

> BD-R Up to 6X BD-RE SL/DL Up to 6X BD-RE TL Up to 4X **DVD-ROM Up to 8X** DVD-R SL/DL Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R SL/DL Up to 8X DVD+R Up to 8X DVD+RW Up to 8X

BDMV (AACS Compliant Disc) Up to 6x/2x (Read/Play)



Technical Specifications – Storage

DVD-RAM Up to 5x

DVD-Video (CSS Compliant Disc)

Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x

CD-DA (DAE) Up to 24X/10X (Read/Play)

Access time Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical),

(typical reads, including CD-ROM: 165 ms (typical)

settling) Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical),

CD-ROM: 340 ms (typical)

Power Source Slimline SATA DC power receptacle

DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC -1200 mA typical, 2000 mA maximum

Environmental conditions Temperature 41° to 122° F (5° to 50° C)

(operating - non- Relative Humidity 10% to 80%

condensing) Maximum Wet Bulb Temperature 84° F (29° C)





Technical Specifications – Networking and Communications

NETWORKING AND COMMUNICATIONS

Realtek RTK8111FP 10/100/1	1000 Integrated NIC	
Connector	RJ-45	
System Interface	PCIe + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)	
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)	
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)	
	Auto-Negotiation (Automatic Speed Selection)	
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support	
	IEEE 802.1q VLAN support	
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)	
	IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable)	
	Protocol Offload (ARP & NS)	
	Large send offload and Giant send offload	
	Receiving Side Scaling	
	Jumbo Frame 9K	
Power consumption	Cable Disconnection: 25mW	
	100Mbps Full Run: 450mW	
	1000bp Full Run: 1000mW	
	WoL Enable(S3/S4/S5): 50mW	
	WoL Disable(S3/S4/S5): 25mW	
Power	ACPI compliant – multiple power modes	
Management	Situation-sensitive features reduce power consumption	
	Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame);	
	Wake-on-LAN from off (Magic Packet only)	
	PXE 2.1 Remote Boot	
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)	
	Comprehensive diagnostic and configuration software suite	
	Virtual Cable Doctor for Ethernet cable status	
Security & Manageability	Support DASH 1.2 compliant	

Intel® Wi-Fi 6 AX200 + BT5 (802.	.11ax 2x2, supporting gigabit file transfer speeds)
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Features Wi-Fi 6 technology
Frequency Band	802.11b/g/n/ax
	• 2.402 – 2.482 GHz



	802.11a/n/ac/ax
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
Floudiation	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	טוטוי, טו אר, עו אר, ככת, דס עחויו, טד עחויו, באס עחויו, דטבדעחויו
Security ³	• IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only
Security	• AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	802.11b:+18.5dBm minimum
output Power-	
	• 802.11g : +17.5dBm minimum
	• 802.11a : +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum
	• 802.11n HT20(5GHz) : +15.5dBm minimum
	• 802.11n HT40(5GHz) : +14.5dBm minimum
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum
	• 802.11ac VHT160(5GHz): +11.5dBm minimum
	• 802.11ax HT40(2.4GHz): +10dBm minimum
	• 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	• Transmit mode 2.0 W
	Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	• Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ³	•802.11b, 1Mbps : -93.5dBm maximum
	•802.11b, 11Mbps : -84dBm maximum
	• 802.11a/g, 6Mbps : -86dBm maximum
	• 802.11a/g, 54Mbps : -72dBm maximum
	• 802.11n, MCS07 : -67dBm maximum
	• 802.11n, MCS15 : -64dBm maximum
	• 802.11ac, MCS0 : -84dBm maximum
	• 802.11ac, MCS9 : -59dBm maximum
	- 002.1 rac, 1-000m maximum



Г	T			
	• 802.11ax, MCS11(HT40): -59dBm maximum			
	• 802.11ax, MCS11(VHT160): -58.5dBm maximum			
Antenna type	High efficiency and	tenna with spatial diversity, mounted in the display enclosure		
	Two ambaddad du	in hand 2.4/F Clie antennes are provided to the sayd to support MI AN		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support MIMO communications and Bluetooth communications			
Form Factor	PCI-Express M.2 MiniCard			
Dimensions	1. Type 2230 : 2.3			
Dilliensions	- · · · · · · · · · · · · · · · · · · ·	7 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8			
	2. Type 126: 1.3g	9		
Operating Voltage	3.3v +/- 9%			
Temperature	Operating	14° to 158° F (–10° to 70° C)		
•	Non-operating	-40° to 176° F (-40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
-	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio	o OFF; LED Off – Radio ON		
HP Integrated Module with Blueto	oth 4.0/4.1/4.2/5.0/5	.1 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0/5.1	Compliant		
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)			
	BLE: 0~39 (2 MHz/0	CH)		
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps			
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps			
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels			
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or			
	864 kbps symmetric (3-EV5)			
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth device with a maximum			
	transmit power of +	+ 9.5 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW			
	Peak (Rx) 230 mW			
	Selective Suspend 17 mW			
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software			
Link Topology				
Power Management	Microsoft Windows ACPI, and USB Bus Support			
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Power Management	ETS 300 328, ETS 300 826			
	2.3 300 320, 213 300 020			
Certifications	Low Voltage Directive IEC950			
UL, CSA, and CE Mark		rk		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Co	ompliance		
	LE Link Layer Ping			
	LE Dual Mode			
	LE Link Layer			
	LE Low Duty Cycle Directed Advertising			
	LE L2CAP Connection Oriented Channels			
	Train Nudging & Interlaced Scan			
	BT4.2 ESR08 Comp	uance		



LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822CE 802.11ac 2x2	Wi-Fi + BT5		
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Wi-Fi® CERTIFIED™		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	• 802.1x authentication		
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	• 802.11b : +14dBm minimum		
	• 802.11g : +12dBm minimum		
	• 802.11a: +12dBm minimum		
	• 802.11n HT20(2.4GHz): +12dBm minimum		
	• 802.11n HT40(2.4GHz) : +12dBm minimum		



		GHz): +10dBm minimum	
	-	GHz): +10dBm minimum	
		(5GHz): +10dBm minimum	
Power Consumption	• Transmit mode2	· · · ·	
	• Receive mode		
		180 mW (WLAN Associated)	
		V (WLAN unassociated)	
	Connected Stand	- -	
	• Radio disabled 8		
Power Management		ess compliant power management	
		power saving mode	
Receiver Sensitivity ³		93.5dBm maximum	
		-84dBm maximum	
		:: -86dBm maximum	
		os: -72dBm maximum	
	802.11n, MCS07: -		
	802.11n, MCS15: -		
	802.11ac, MCS0: -		
Autousetuse	802.11ac, MCS9: -		
Antenna type	High efficiency and	tenna with spatial diversity, mounted in the display enclosure	
	The combadded dead band 2.4/5 CHa automass are availed to the court to come out MI AN		
		ial band 2.4/5 GHz antennas are provided to the card to support WLAN tions and Bluetooth communications	
Farms Factor			
Form Factor	•	liniCard with CNVi Interface	
Dimensions	1. Type 2230 : 2.3		
141-2-1-4		7 x 12.0 x 16.0 mm	
Weight	1. Type 2230 : 2.8	g	
O	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%	140. 4500 F (400. 500 G)	
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
Aloto I	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio	,	
	LED Off – Radio Of	V	
HP Integrated Module with Blueto	oth 4.0/4.1/4.2/5.0 W	ireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MF	Hz/CH)	
	BLE: 0~39 (2 MHz/0		
Data Rates and Throughput	Legacy: 3 Mbps dat	a rate; throughput up to 2.17 Mbps	
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or		
	864 kbps symmetri		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum		
	transmit power of + 4 dBm for BR and EDR.		
Dower Concumption	Peak (Tx) 330 mW		
Power Consumption	Peak (1x) 330 mW		
	Selective Suspend 17 mW		
	perective Suspend	1 / 111VV	



Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software			
Power Management	ETS 300 328, ETS 300 826			
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Power Management	ETS 300 328, ETS 300 826			
Certifications	Low Voltage Directive IEC950			
	UL, CSA, and CE Mark			
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance			
	LE Link Layer Ping			
	LE Dual Mode			
	LE Link Layer			
	LE Low Duty Cycle Directed Advertising			
	LE L2CAP Connection Oriented Channels			
	Train Nudging & Interlaced Scan			
	BT4.2 ESR08 Compliance			
	LE Secure Connection- Basic/Full			
	LE Privacy 1.2 –Link Layer Privacy			
	LE Privacy 1.2 –Extended Scanner Filter Policies			
	LE Data Packet Length Extension			
	FAX Profile (FAX)			
	Basic Imaging Profile (BIP)2			
	Headset Profile (HSP)			
	Hands Free Profile (HFP)			
	Advanced Audio Distribution Profile (A2DP)			



Technical Specifications – Input/Output Devices

I/O DEVICES

Mechanical

HP USB Premium Keyboard

Keys 104, 105 layout (depending upon country)

Physical Characteristics Dimensions (L x W x H) 17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)

Weight 1.54 lb (698g)

Operating voltage 5 VDC, +/-5%

Power consumption 35mA (All LED on)

Electrical System interface USB Type A plug connector

ESD Contact Discharge: 8 KV Air Discharge: 15 KV

EMI - RFI Conforms to FCC rules for a Class B computing device

Keycaps Low-profile design

Switch actuation 60±10g nominal peak force with tactile feedback

Switch life 10 million keystrokes (Life tester)

Switch type Contamination-resistant switch membrane

Key-leveling mechanisms For all double-wide and greater-length keys

Cable length 6 ft (1.8 m)

Acoustics 43-dBA maximum sound pressure level

Operating temperature 50° to 122° F (10° to 50° C)

Non-operating temperature -22° to 140° F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)
Non-operating humidity 20% to 80% (non-condensing at ambient)

Environmental Operating shock 40 g, six surfaces

Non-operating shock 80 g, six surfaces

Operating vibration 2-g peak acceleration

Non-operating vibration 4-g peak acceleration

Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence

Drop (in box) 30 in (76.2 cm) on concrete, 16-drop sequence

Approvals UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC

Ergonomic Compliance TUVGS

Kit Contents Keyboard, QSP Warranty Card Product Notice



Technical Specifications – Input/Output Devices

HP USB Premium Mouse

Dimensions (H x L x W) 4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)

Weight 0.19lb (90g)

Operating temperature 50° to 122°F (10° to 50° C) Non-operating temperature -22° to 140°F (-30° to 60° C)

Operating humidity 10% to 90% (non-condensing at ambient)

Non-operating humidity 20% to 80% (non condensing at ambient)

Environmental Operating shock 50 g, 6 surfaces

Non-operating shock 80 g, 6 surfaces

Operating vibration 2 g peak acceleration Non-operating vibration 4 g peak acceleration

Operating voltage 5 VDC, +/-5%

Electrical Power consumption 12mA

Connector USB 2.0

Type 3D mouse (3 keys and wheel)

Resolution 800, 1200, 1600 DPI Sensor Pixart PAN3606DL

Tracking acceleration 8G(max), 1G=9.8m/s2

Tracking speed Cable length 6 ft (1.8 m)

Color Jack Black

Regulatory approvals Compliant UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC

HP Wired Desktop 320M Mouse

Dimensions (H x L x W) 35.5mm x 103.8mm x 63.4mm

Weight 75.8 +/- 10 g

ColorBlackConnectorUSB

Cable Length 1800mm

Sustainability Low halogen PCBA

Resolution 1000 DPI sensitivity

Buttons Two primary buttons and clickable scroll wheel

HP Wired Desktop 320K Keyboard

Dimensions (H x L x W) 16.7mm x 426.2mm x 110.9mm

Weight 413 +/- 30 q

Connector Black
USB

Cable Length 1800mm



Mechanical

Technical Specifications – Input/Output Devices

Keys 104, 105, 107, 109

Operating Voltage 5V

Power Consumption 50mA – 100mA

Switch Life 10M

Operating Temperature 10°C to 50°C

Non- Operating Temperature

Switch Type

30°C to 65°C

Plunger

Operating Humidity 10% to 90% Non- Operating Humidity 0% to 90%

Sustainability Greater than 50% post-consumer recycled plastic content and low halogen PCBA

HP USB Mouse

Mechanical

Dimensions (H x L x W) 37mm*115mm*62.9mm

Weight 90 +10g/- 5 g

Color Black **Connector** USB

Resolution 800 DPI sensitivity

Buttons Two primary buttons and clickable scroll wheel



Technical Specifications – Audio/Multimedia

AUDIO/MULTIMEDIA

HP EliteDesk 805 G6 Small Form Factor Business PC

Type Integrated

HD Stereo Codec Conexant Zuma CX20632

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: Line-out

Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

externally

Multi-streaming Capable Playback multi-streaming allows for independent audio streams to be sent to/from the front and

rear jacks or integrated speaker

Sampling Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Synthesis Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP EliteDesk 805 G6 Desktop Mini Business PC

Type Integrated

HD Stereo Codec Conexant Zuma ALC3205

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port

All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

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to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Synthesis Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes



Technical Specifications – Power

POWER

HP EliteDesk 805 G6 Small Form Factor Business PC UNIT ENVIRONMENT AND OPERATING CONDITIONS

Temperature Range Operating: 5°C ~50°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft (15240 m)

HP EliteDesk 805 G6 Desktop Mini Business PC UNIT ENVIRONMENT AND OPERATING CONDITIONS

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft (15240 m)

DM SFF

80 PLUS Platinum		180W active PFC 87/90/87% efficient at 20/50/100% load (115V) 90/92/89% efficient at 20/50/100% load (230V 210W active PFC 90/92/89% efficient at 20/50/100% load(115V) 91/93/90% efficient at 20/50/100% load(230V)
	External power supply 65W EPS, 88% average efficiency at 115V & 89% at 230Vac 90W EPS, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, 88% average efficiency at 115V & 89% at 230Vac	Internal power supply
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ
	65W≦1.6A 90W≦1.2A 150WW≦2.2A	180W≦2.3A 210W≦2.5A



Technical Specifications – Power

Rated Input Current with Energy Efficient* Power Supply	65W≦1.6A	180W≦2.3A
	90W≦1.2A	210W ≦2.5A
	150WW≦2.2A	210W =2.3A
DC Output	+19.5V	+12V
-	1	
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of	Less than 500 microamps of
	leakage current at 120 Vac with	leakage current at 120 Vac with
	the ground wire disconnected,	the ground wire disconnected,
	as required for Non-patient	as required for Non-patient
	Electrical Appliances and	Electrical Appliances and
	Equipment used in a patient	Equipment used in a patient
	care facility or that contact	care facility or that contact
	patients in normal use. Per	patients in normal use. Per
	section 10.3.5.1.	section 10.3.5.1.
	Less than 100 microamps of	Less than 100 microamps of
	leakage current at 120 Vac with	leakage current at 120 Vac with
	the ground wire intact with	the ground wire intact with
	normal polarity, as required for	normal polarity, as required for
	Non-patient Electrical	Non-patient Electrical
	Appliances and Equipment used	Appliances and Equipment used
	in a patient care facility or that	in a patient care facility or that
	contact patients in normal use.	contact patients in normal use.
	Per section 10.3.5.1.	Per section 10.3.5.1.
Power Supply Fan	N/A	50mm variable speed
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
Dimensions	65W : 113.5mm x 55mm x	200mm x 85mm x 53mm
	30mm	
	90W : 132.5mm x 57mm x	
	30.3mm	
	150W : 167.5mm x 80mm x	
	40.5mm	

The harmonic input current requirements must be met under the following operating conditions:

Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated Load	-	85%	88%	90%	92%	115Vac/60HZ
	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated Load	70%	82%	85%	87%	89%	115Vac/60HZ
100% of Rateu Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ



Technical Specifications – Weights and Dimensions

WEIGHTS & DIMENSIONS

	<u>DM</u>	<u>SFF</u>
Chassis (W x D x H) Not including bezel	6.97 x 6.89 x 1.35 in 177 x 175 x 34.2 mm	3.84 x 10.63 x 11.93 in 97.5 x 270 x 303 mm
System Volume	64 cu in 1.05 L	747cu in 7.8L
Max System Weight	1.45kg	4.89KG
Max Supported Weight (desktop orientation)	0	77 lb 35kg
Stand Dimensions	160x117x18.5mm	200 x 152 x 372 mm
Packaging (W x D x H)	19.57 x 5.04 x 8.78 in 497 x 128 x 223 mm	15.71 x 9.06 x 19.65 in 399 x 230 x 499 mm
Shipping Weight	2.95 kg 6.49 lb	16.12 lb. 7.32 kg
Shipping Weight (Molded Pulp)	3.05 kg 6.72 lb	16.62 lb 7.54kg
Multipack Packaging (10 units)	20.28x16.54x25 in 515x420x636 mm	
Palletization Profile	10-units per layer 11, 15, or 18 layers max depending on details of freight 110 units per air freight pallet 46.26 x 39.21 x 62.87 in 1175 x 996 x 1597 mm (include pallet), or 150 units per standard ground or sea freight pallet 46.26 x 39.21 x 83.86 in 1175 x 996 x 2130 mm (include pallet), or 180 units per ground freight or high-cube sea pallet 46.26 x 39.21 x 99.45 in 1175 x 996 x 2526 mm (include pallet)	6-units per layer 60 per pallet 47.24 x 39.37 x 94.49 in (including pallet) 10 layer max



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- System/Private ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- 1 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- NIC LEDs (integrated) (Green & Amber)
- HD LED To Indicate Normal Operations
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board
- Tool-less Hard drive & DVD drive Removal
- Green Pull Tabs, and Quick Release Latches for easy Identification



Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, and DM only. DM requires optional stand.
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only)
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM

NOTE: Storage Drive lock does not work with Self Encrypting storage



After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>DM</u>	<u>SFF</u>	Part Number
AMD® Radeon™ R7 430 2GB 2 DisplayPort™ 64bit Card		X	5LH79AA
AMD® Radeon™ R7 430 2GB DisplayPort™ VGA 64bit Card¹		X	5JW81AA
AMD® Radeon™ RX550X 4GB DisplayPort™ Card		X	5LH79AA
1 Not available in all regions			

Desktop Mini Accessories	<u>DM</u>	<u>SFF</u>	Part Number
HP Desktop Mini Port Cover v3	X (discrete GPU not supported)		13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	X (discrete GPU not supported)		13L70AA
HP Desktop Mini 65W Power Supply Kit	X		L2X04AA
HP Desktop Mini 90W Power Supply Kit	X		L4R65AA
HP Desktop Mini LockBox V2 ¹	X (discrete GPU not supported)		3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	X		K9Q83AA
HP Desktop Mini I/O Expansion Module	X		K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v31	X (discrete GPU not supported)		13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder ¹	X (discrete GPU not supported)		13L68AA
HP B250 PC Mounting Bracket	X		<u>8RA46AA</u>
HP B300 PC Mounting Bracket	X		2DW53AA
HP B300 PC Mounting Bracket with Power Supply Holder	X		7DB37AA
HP B500 PC Mounting Bracket	X		2DW52AA
HP Desktop Mini Vertical Chassis Stand	X	-	G1K23AA
HP DM VESA Power Supply Holder Kit v2	X (discrete GPU not supported)		7DB38AA
HP Quick Release Bracket 2	Х		6KD15AA

Data Storage Drives	<u>DM</u>	<u>SFF</u>	Part Number
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X8U75AA
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive		X	QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive		X	QK555AA
HP 9.5mm DVD Writer		X	1CA53AA



1.Not available in all regions

After Market Options

Input Devices	<u>DM</u>	<u>SFF</u>	<u>Part Number</u>
HP Desktop Wired 320K Keyboard	Х	X	9SR37AA
HP Desktop Wired 320MK Mouse and Keyboard	Х	X	9SR36AA
HP Wireless Business Slim Keyboard and Mouse	Х	X	N3R88AA
HP USB Buisness Slim CCID SmartCard Keyboard	Х	Х	Z9H48AA
HP USB Keyboard	Х	Х	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	Х	Х	1VD81AA
HP USB Premium Keyboard	Х	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	Х	Х	BU207AA
HP Wireless Premium Keyboard	Х	X	Z9N41AA
HP PS/2 Business Slim Keyboard		X	N3R86AA
HP Desktop Wired 320M Mouse	Х	Х	9VA80AA
HP USB Fingerprint Mouse	Х	X	4TS44AA
HP USB Premium Mouse	Х	Х	1JR32AA
HP PS/2 Mouse		X	QY775AA
HP Wireless Premium Mouse	Х	Х	1JR31AA
HP USB 1000dpi Laser Mouse	Х	Х	QY778AA
HP USB Optical Mouse	Х	Х	QY777AA

System Memory	<u>DM</u>	<u>SFF</u>	Part Number
HP 4GB DDR4-3200 DIMM		Х	13L78AA
HP 8GB DDR4-3200 DIMM		Х	13L76AA
HP 16GB DDR4-3200 DIMM		X	13L74AA
HP 32GB DDR4-3200 DIMM		X	13L72AA
HP 4GB DDR4-3200 SODIMM	X		13L79AA
HP 8GB DDR4-3200 SODIMM	X		13L77AA
HP 16GB DDR4-3200 SODIMM	X		13L75AA
HP 32GB DDR4-3200 SODIMM	X		13L73AA

Multimedia Devices	<u>DM</u>	<u>SFF</u>	Part Number
HP Business Headset v2	Х	Х	T4E61AA
HP S101 Speaker Bar	Х	Х	5UU40AA
HP UC Speaker Phone v2	Х		4VW02AA



After Market Options

Security Devices	<u>DM</u>	<u>SFF</u>	Part Number
HP Business PC Security Lock v3 Kit		X	3XJ17AA
HP Dual Head Keyed Cable Lock		X	T1A64AA
HP Keyed Cable Lock 10mm	Х	X	T1A62AA
HP Master Keyed Cable Lock 10mm	Х	X	T1A63AA
HP Sure Key Cable lock	Х		6UW42AA

I/O Devices	<u>DM</u>	<u>SFF</u>	<u>Part Number</u>
HP DisplayPort Port Flex IO v2	X (discrete GPU not supported)	х	13L54AA
HP HDMI Port Flex IO v2	X (discrete GPU not supported)	х	13L55AA
HP Type-C USB 3.1 Gen2 Port Flex IO v2	Х	X	<u>13L59AA</u>
HP Type-C USB 3.1 Gen2 Port with PD Flex IO v2	X (discrete GPU not supported)		<u>13L60AA</u>
HP VGA Port Flex IO v2	X (discrete GPU not supported)	Х	<u>13L53AA</u>
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (discrete GPU not supported)		13L58AA
HP Serial Port Flex IO v2	X (discrete GPU not supported)	Х	3TK76AA
HP Serial Port Flex IO 2 v2	X (discrete GPU not supported)		<u>13L57AA</u>
HP USB to Serial Port Adapter		X	J7B60AA
HP USB-C to Display Port Adapter		X	N9K78AA
HP DisplayPort To HDMI True 4k Adapter	Х	X	2JA63AA
HP DVI Cable Kit		X	DC198A
HP HDMI Standard Cable Kit	Х	X	T6F94AA
HP DisplayPort Cable Kit	Х	X	VN567AA
HP DisplayPort To DVI-D Adapter	Х	X	FH973AA
HP DisplayPort To VGA Adapter	х	X	AS615AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607



Change Log

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Date	Version History	Action	Description of Change
October 15, 2020	From v1 to v2	Update	Environmental specs for SFF
November 4, 2020	From v2 to v3	Update	NVIDIA statements and it's footnote At a glance section
November 17, 2020	From v3 to v4	Correction	System Integrated Graphics name corrected
November 18, 2020	From v4 to v5	Addition	Environmental data for DM
November 26, 2020	From v5 to v6	Correction	HDMI port version in both rear call outs sections
December 22, 2020	From v6 to v7	Addition	Security section

